

CD4011B, CD4012B, CD4023B Types

CMOS NAND GATES

High-Voltage Types (20-Volt Rating)

- Quad 2 Input – CD4011B
- Dual 4 Input – CD4012B
- Triple 3 Input – CD4023B

■ CD4011B, CD4012B, and CD4023B NAND gates provide the system designer with direct implementation of the NAND function and supplement the existing family of CMOS gates. All inputs and outputs are buffered.

The CD4011B, CD4012B, and CD4023B types are supplied in 14-lead hermetic dual-in-line ceramic packages (F3A suffix), 14-lead dual-in-line plastic packages (E suffix), 14-lead small-outline packages (M, MT, M96, and NSR suffixes), and 14-lead thin shrink small-outline packages (PWR suffix). The CD4011B and CD4023B types also are supplied in 14-lead thin shrink small-outline packages (PW suffix).

Features:

- Propagation delay time = 60 ns (typ.) at $C_L = 50$ pF, $V_{DD} = 10$ V
- Buffered inputs and outputs
- Standardized symmetrical output characteristics
- Maximum input current of $1 \mu A$ at 18 V over full package temperature range; 100 nA at 18 V and 25°C
- 100% tested for quiescent current at 20 V
- 5-V, 10-V, and 15-V parametric ratings
- Noise margin (over full package temperature range):
 - 1 V at $V_{DD} = 5$ V
 - 2 V at $V_{DD} = 10$ V
 - 2.5 V at $V_{DD} = 15$ V

- Meets all requirements of JEDEC Tentative Standard No. 13B, "Standard Specifications for Description of "B" Series CMOS Devices"

MAXIMUM RATINGS, Absolute-Maximum Values:

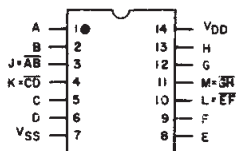
| | | |
|--|-----------------------------|--------------------------|
| DC SUPPLY-VOLTAGE RANGE, (V_{DD}) | | |
| Voltages referenced to V_{SS} Terminal | | -0.5V to +20V |
| INPUT VOLTAGE RANGE, ALL INPUTS | | |
| | | -0.5V to $V_{DD} + 0.5V$ |
| DC INPUT CURRENT, ANY ONE INPUT | | ±10mA |
| POWER DISSIPATION PER PACKAGE (P_D): | | |
| For $T_A = -55^\circ C$ to $+100^\circ C$ | | 500mW |
| For $T_A = +100^\circ C$ to $+125^\circ C$ | Derate Linearity at 12mW/°C | to 200mW |
| DEVICE DISSIPATION PER OUTPUT TRANSISTOR | | |
| For $T_A =$ FULL PACKAGE-TEMPERATURE RANGE (All Package Types) | | 100mW |
| OPERATING-TEMPERATURE RANGE (T_A) | | -55°C to +125°C |
| STORAGE TEMPERATURE RANGE (T_{stg}) | | -65°C to +150°C |
| LEAD TEMPERATURE (DURING SOLDERING): | | |
| At distance $1/16 \pm 1/32$ inch (1.59 ± 0.79mm) from case for 10s max | | +265°C |

RECOMMENDED OPERATING CONDITIONS

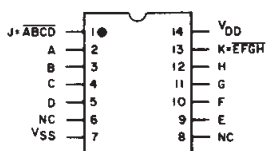
For maximum reliability, nominal operating conditions should be selected so that operation is always within the following ranges:

| CHARACTERISTIC | LIMITS | | UNITS |
|---|--------|------|-------|
| | MIN. | MAX. | |
| Supply-Voltage Range (For $T_A =$ Full Package Temperature Range) | 3 | 18 | V |

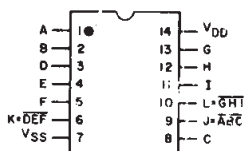
TERMINAL ASSIGNMENTS



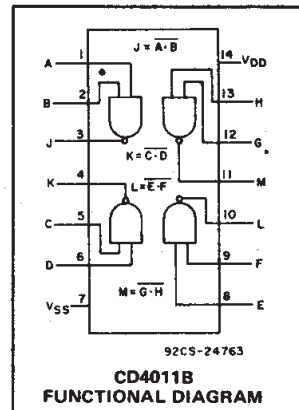
CD4011B



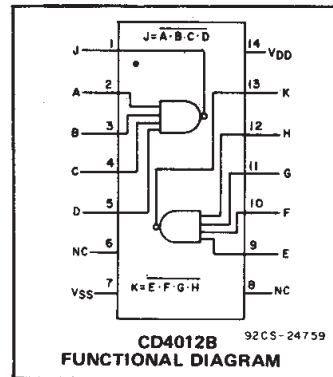
CD4012B



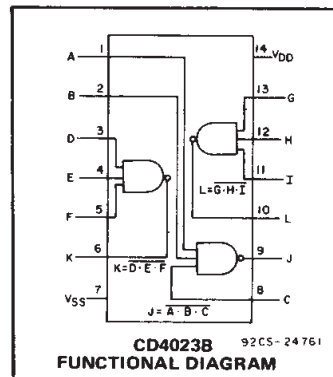
CD4023B



CD4011B
FUNCTIONAL DIAGRAM



CD4012B
FUNCTIONAL DIAGRAM



CD4023B
FUNCTIONAL DIAGRAM

CD4011B, CD4012B, CD4023B Types

STATIC ELECTRICAL CHARACTERISTICS

| CHARACTERISTIC | CONDITIONS | | | LIMITS AT INDICATED TEMPERATURES (°C) | | | | | | | UNITS |
|--|--------------------|---------------------|---------------------|---------------------------------------|-------|-------|-------|-------|-------------------|------|-------|
| | V _O (V) | V _{IN} (V) | V _{DD} (V) | -55 | -40 | +85 | +125 | +25 | | | |
| | | | | | | | | Min. | Typ. | Max. | |
| Quiescent Device Current, I _{DD} Max. | - | 0,5 | 5 | 0.25 | 0.25 | 7.5 | 7.5 | - | 0.01 | 0.25 | μA |
| | - | 0,10 | 10 | 0.5 | 0.5 | 15 | 15 | - | 0.01 | 0.5 | |
| | - | 0,15 | 15 | 1 | 1 | 30 | 30 | - | 0.01 | 1 | |
| | - | 0,20 | 20 | 5 | 5 | 150 | 150 | - | 0.02 | 5 | |
| Output Low (Sink) Current I _{OL} Min. | 0.4 | 0,5 | 5 | 0.64 | 0.61 | 0.42 | 0.36 | 0.51 | 1 | - | mA |
| | 0.5 | 0,10 | 10 | 1.6 | 1.5 | 1.1 | 0.9 | 1.3 | 2.6 | - | |
| | 1.5 | 0,15 | 15 | 4.2 | 4 | 2.8 | 2.4 | 3.4 | 6.8 | - | |
| Output High (Source) Current, I _{OH} Min. | 4.6 | 0,5 | 5 | -0.64 | -0.61 | -0.42 | -0.36 | -0.51 | -1 | - | mA |
| | 2.5 | 0,5 | 5 | -2 | -1.8 | -1.3 | -1.15 | -1.6 | -3.2 | - | |
| | 9.5 | 0,10 | 10 | -1.6 | -1.5 | -1.1 | -0.9 | -1.3 | -2.6 | - | |
| Output Voltage: Low-Level, V _{OL} Max. | - | 0,5 | 5 | 0.05 | | | | - | 0 | 0.05 | V |
| | - | 0,10 | 10 | 0.05 | | | | - | 0 | 0.05 | |
| | - | 0,15 | 15 | 0.05 | | | | - | 0 | 0.05 | |
| Output Voltage: High-Level, V _{OH} Min. | - | 0,5 | 5 | 4.95 | | | | 4.95 | 5 | - | V |
| | - | 0,10 | 10 | 9.95 | | | | 9.95 | 10 | - | |
| | - | 0,15 | 15 | 14.95 | | | | 14.95 | 15 | - | |
| Input Low Voltage, V _{IL} Max. | 4.5 | - | 5 | 1.5 | | | | - | - | 1.5 | V |
| | 9 | - | 10 | 3 | | | | - | - | 3 | |
| | 13.5 | - | 15 | 4 | | | | - | - | 4 | |
| Input High Voltage, V _{IH} Min. | 0.5, 4.5 | - | 5 | 3.5 | | | | 3.5 | - | - | V |
| | 1.9 | - | 10 | 7 | | | | 7 | - | - | |
| Input Current I _{IN} Max. | | 0,18 | 18 | ±0.1 | ±0.1 | ±1 | ±1 | - | ±10 ⁻⁵ | ±0.1 | μA |



Fig. 1 - Typical voltage transfer characteristics.



Fig. 2 - Typical power dissipation characteristics.

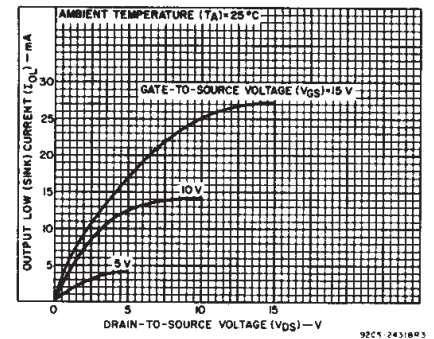


Fig. 3 - Typical output low (sink) current characteristics.

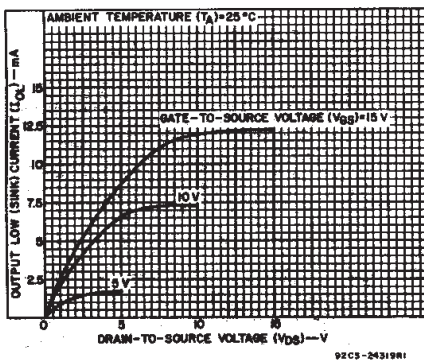


Fig. 4 - Minimum output low (sink) current characteristics.

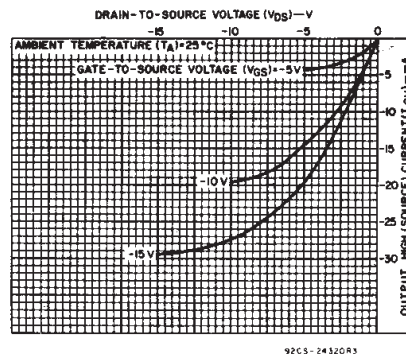


Fig. 5 - Typical output high (source) current characteristics.

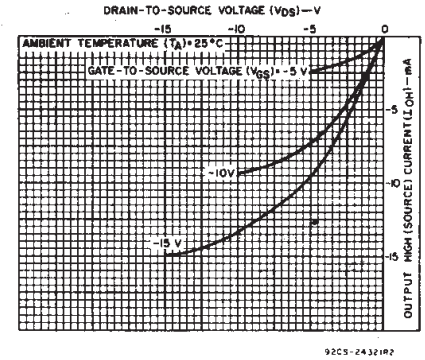
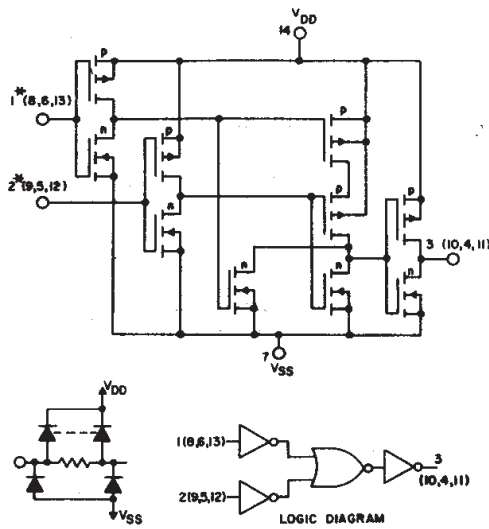


Fig. 6 - Minimum output high (source) current characteristics.

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COMMERCIAL CMOS
HIGH VOLTAGE ICs

CD4011B, CD4012B, CD4023B Types



* ALL INPUTS ARE PROTECTED BY CMOS PROTECTION NETWORK

1 OF 4 GATES (NUMBERS IN PARENTHESES ARE TERMINAL NUMBERS FOR OTHER GATES)

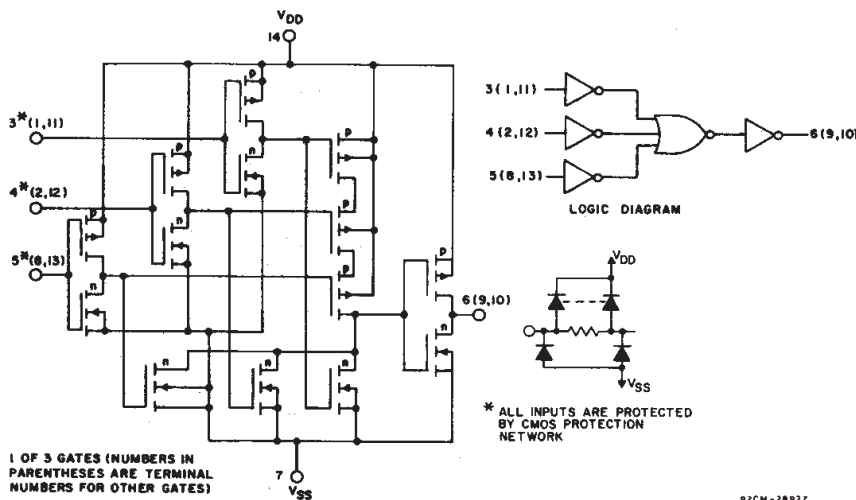
Fig.7 - Schematic and logic diagrams for CD4011B.



1 OF 2 GATES (NUMBERS IN PARENTHESES ARE TERMINAL NUMBERS FOR OTHER GATES)

92CM - 26926

Fig.8 - Schematic and logic diagrams for CD4012B.



1 OF 3 GATES (NUMBERS IN PARENTHESES ARE TERMINAL NUMBERS FOR OTHER GATES)

* ALL INPUTS ARE PROTECTED BY CMOS PROTECTION NETWORK

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Fig. 9 - Schematic and logic diagrams for CD4023B.

DYNAMIC ELECTRICAL CHARACTERISTICS

At $T_A = 25^\circ\text{C}$; Input $t_r, t_f = 20\text{ ns}$, $C_L = 50\text{ pF}$, $R_L = 200\text{ k}\Omega$

| CHARACTERISTIC | TEST CONDITIONS | LIMITS | | UNITS | |
|--|-----------------|-----------------------|------|-------|------|
| | | V _{DD} VOLTS | TYP. | | MAX. |
| Propagation Delay Time, t_{PHL}, t_{PLH} | | 5 | 125 | 250 | ns |
| | | 10 | 60 | 120 | |
| | | 15 | 45 | 90 | |
| Transition Time, t_{THL}, t_{TLH} | | 5 | 100 | 200 | ns |
| | | 10 | 50 | 100 | |
| | | 15 | 40 | 80 | |
| Input Capacitance, C_{IN} | Any Input | | 5 | 7.5 | pF |

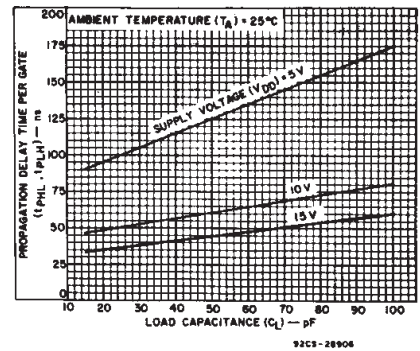


Fig.10 - Typical propagation delay time per gate as a function of load capacitance.

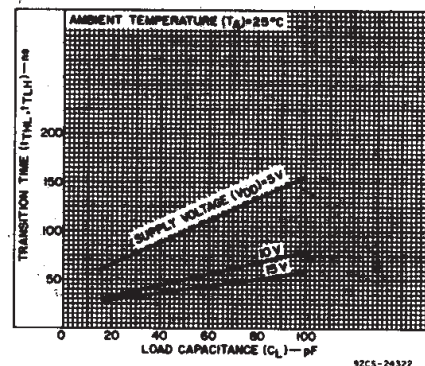


Fig.11 - Typical transition time as a function of load capacitance.

CD4011B, CD4012B, CD4023B Types

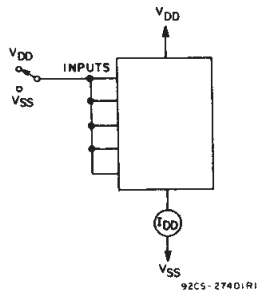


Fig. 12 - Quiescent-device-current test circuit.



Fig. 13 - Input-voltage test circuit.

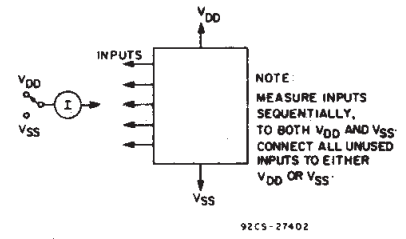


Fig. 14 - Input-current test circuit.

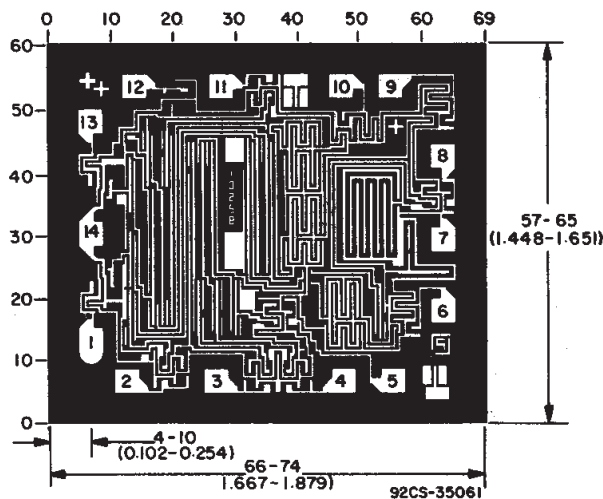
Chip Dimensions and Pad Layouts



CD4011BH



CD4012BH



CD4023BH

Dimensions in parentheses are in millimeters and are derived from the basic inch dimensions as indicated. Grid graduations are in mils (10^{-3} inch).

3
COMMERCIAL CMOS
HIGH VOLTAGE ICs

PACKAGING INFORMATION

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| 89265AKB3T | OBSOLETE | CFP | WR | 14 | | TBD | Call TI | Call TI | -55 to 125 | | |
| 89266AKB3T | OBSOLETE | CFP | WR | 16 | | TBD | Call TI | Call TI | -55 to 125 | | |
| 89273AKB3T | OBSOLETE | CFP | WR | 14 | | TBD | Call TI | Call TI | -55 to 125 | | |
| CD4011BE | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD4011BE | Samples |
| CD4011BEE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD4011BE | Samples |
| CD4011BF | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | CD4011BF | Samples |
| CD4011BF3A | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | CD4011BF3A | Samples |
| CD4011BF3AS2534 | OBSOLETE | CDIP | J | 14 | | TBD | Call TI | Call TI | | | |
| CD4011BK3 | OBSOLETE | CFP | WR | 14 | | TBD | Call TI | Call TI | -55 to 125 | | |
| CD4011BM | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4011BM | Samples |
| CD4011BM96 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4011BM | Samples |
| CD4011BM96E4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4011BM | Samples |
| CD4011BM96G4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4011BM | Samples |
| CD4011BME4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4011BM | Samples |
| CD4011BMG4 | ACTIVE | SOIC | D | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| CD4011BMT | ACTIVE | SOIC | D | 14 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4011BM | Samples |
| CD4011BMTE4 | ACTIVE | SOIC | D | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| CD4011BMTG4 | ACTIVE | SOIC | D | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| CD4011BNSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4011B | Samples |
| CD4011BNSRE4 | ACTIVE | SO | NS | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| CD4011BNSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4011B | Samples |
| CD4011BPW | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM011B | Samples |
| CD4011BPWE4 | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM011B | Samples |
| CD4011BPWG4 | ACTIVE | TSSOP | PW | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| CD4011BPWR | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM011B | Samples |
| CD4011BPWRE4 | ACTIVE | TSSOP | PW | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| CD4011BPWRG4 | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM011B | Samples |
| CD4012BE | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD4012BE | Samples |
| CD4012BEE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD4012BE | Samples |
| CD4012BF3A | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | CD4012BF3A | Samples |
| CD4012BF3AS2534 | OBSOLETE | CDIP | J | 14 | | TBD | Call TI | Call TI | | | |
| CD4012BM | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4012BM | Samples |
| CD4012BM96 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4012BM | Samples |
| CD4012BM96E4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4012BM | Samples |
| CD4012BM96G4 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4012BM | Samples |
| CD4012BME4 | ACTIVE | SOIC | D | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| CD4012BMG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4012BM | Samples |
| CD4012BMT | ACTIVE | SOIC | D | 14 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4012BM | Samples |
| CD4012BMTE4 | ACTIVE | SOIC | D | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|--------------------|------|----------------|----------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| CD4012BMTG4 | ACTIVE | SOIC | D | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| CD4012BNSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4012B | Samples |
| CD4012BNSRE4 | ACTIVE | SO | NS | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| CD4012BNSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4012B | Samples |
| CD4012BPWR | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM012B | Samples |
| CD4012BPWRE4 | ACTIVE | TSSOP | PW | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| CD4012BPWRG4 | ACTIVE | TSSOP | PW | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| CD4023BE | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD4023BE | Samples |
| CD4023BEE4 | ACTIVE | PDIP | N | 14 | 25 | Pb-Free (RoHS) | CU NIPDAU | N / A for Pkg Type | -55 to 125 | CD4023BE | Samples |
| CD4023BF | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | CD4023BF | Samples |
| CD4023BF3A | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | CD4023BF3A | Samples |
| CD4023BF3AS2534 | OBSOLETE | CDIP | J | 14 | | TBD | Call TI | Call TI | | | |
| CD4023BM | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4023BM | Samples |
| CD4023BM96 | ACTIVE | SOIC | D | 14 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4023BM | Samples |
| CD4023BM96E4 | ACTIVE | SOIC | D | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| CD4023BM96G4 | ACTIVE | SOIC | D | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| CD4023BME4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4023BM | Samples |
| CD4023BMG4 | ACTIVE | SOIC | D | 14 | 50 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4023BM | Samples |
| CD4023BMT | ACTIVE | SOIC | D | 14 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4023BM | Samples |
| CD4023BMTE4 | ACTIVE | SOIC | D | 14 | 250 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4023BM | Samples |

| Orderable Device | Status (1) | Package Type | Package Drawing | Pins | Package Qty | Eco Plan (2) | Lead/Ball Finish (6) | MSL Peak Temp (3) | Op Temp (°C) | Device Marking (4/5) | Samples |
|------------------|---------------|--------------|-----------------|------|-------------|-------------------------|-------------------------|----------------------|--------------|-------------------------|-------------------------|
| CD4023BMTG4 | ACTIVE | SOIC | D | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| CD4023BNSR | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4023B | Samples |
| CD4023BNSRE4 | ACTIVE | SO | NS | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| CD4023BNSRG4 | ACTIVE | SO | NS | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CD4023B | Samples |
| CD4023BPW | ACTIVE | TSSOP | PW | 14 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM023B | Samples |
| CD4023BPWE4 | ACTIVE | TSSOP | PW | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| CD4023BPWG4 | ACTIVE | TSSOP | PW | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| CD4023BPWR | ACTIVE | TSSOP | PW | 14 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM | -55 to 125 | CM023B | Samples |
| CD4023BPWRE4 | ACTIVE | TSSOP | PW | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| CD4023BPWRG4 | ACTIVE | TSSOP | PW | 14 | | TBD | Call TI | Call TI | -55 to 125 | | Samples |
| JM38510/05051BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 05051BCA | Samples |
| JM38510/05052BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 05052BCA | Samples |
| JM38510/05053BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 05053BCA | Samples |
| M38510/05051BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 05051BCA | Samples |
| M38510/05052BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 05052BCA | Samples |
| M38510/05053BCA | ACTIVE | CDIP | J | 14 | 1 | TBD | A42 | N / A for Pkg Type | -55 to 125 | JM38510/ 05053BCA | Samples |

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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OTHER QUALIFIED VERSIONS OF CD4011B, CD4011B-MIL, CD4012B, CD4012B-MIL :

● Catalog: [CD4011B](#), [CD4012B](#)

● Military: [CD4011B-MIL](#), [CD4012B-MIL](#)

NOTE: Qualified Version Definitions:

● Catalog - TI's standard catalog product

- Military - QML certified for Military and Defense Applications

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



| | |
|----|---|
| A0 | Dimension designed to accommodate the component width |
| B0 | Dimension designed to accommodate the component length |
| K0 | Dimension designed to accommodate the component thickness |
| W | Overall width of the carrier tape |
| P1 | Pitch between successive cavity centers |

TAPE AND REEL INFORMATION

*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| CD4011BM96 | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4011BMT | SOIC | D | 14 | 250 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4011BNSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| CD4011BPWR | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| CD4012BM96 | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4012BMT | SOIC | D | 14 | 250 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4012BNSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| CD4012BPWR | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| CD4023BM96 | SOIC | D | 14 | 2500 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4023BMT | SOIC | D | 14 | 250 | 330.0 | 16.4 | 6.5 | 9.0 | 2.1 | 8.0 | 16.0 | Q1 |
| CD4023BNSR | SO | NS | 14 | 2000 | 330.0 | 16.4 | 8.2 | 10.5 | 2.5 | 12.0 | 16.0 | Q1 |
| CD4023BPWR | TSSOP | PW | 14 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |

TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|------------|--------------|-----------------|------|------|-------------|------------|-------------|
| CD4011BM96 | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| CD4011BMT | SOIC | D | 14 | 250 | 367.0 | 367.0 | 38.0 |
| CD4011BNSR | SO | NS | 14 | 2000 | 367.0 | 367.0 | 38.0 |
| CD4011BPWR | TSSOP | PW | 14 | 2000 | 367.0 | 367.0 | 35.0 |
| CD4012BM96 | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| CD4012BMT | SOIC | D | 14 | 250 | 367.0 | 367.0 | 38.0 |
| CD4012BNSR | SO | NS | 14 | 2000 | 367.0 | 367.0 | 38.0 |
| CD4012BPWR | TSSOP | PW | 14 | 2000 | 367.0 | 367.0 | 35.0 |
| CD4023BM96 | SOIC | D | 14 | 2500 | 367.0 | 367.0 | 38.0 |
| CD4023BMT | SOIC | D | 14 | 250 | 367.0 | 367.0 | 38.0 |
| CD4023BNSR | SO | NS | 14 | 2000 | 367.0 | 367.0 | 38.0 |
| CD4023BPWR | TSSOP | PW | 14 | 2000 | 367.0 | 367.0 | 35.0 |

J (R-GDIP-T**)

14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



| DIM \ PINS ** | 14 | 16 | 18 | 20 |
|---------------|------------------------|------------------------|------------------------|------------------------|
| A | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC | 0.300 (7,62) BSC |
| B MAX | 0.785 (19,94) | .840 (21,34) | 0.960 (24,38) | 1.060 (26,92) |
| B MIN | — | — | — | — |
| C MAX | 0.300 (7,62) | 0.300 (7,62) | 0.310 (7,87) | 0.300 (7,62) |
| C MIN | 0.245 (6,22) | 0.245 (6,22) | 0.220 (5,59) | 0.245 (6,22) |



4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - $\triangle C$ Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
 - $\triangle D$ Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
 - E. Reference JEDEC MS-012 variation AB.

D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

PW (R-PDSO-G14)

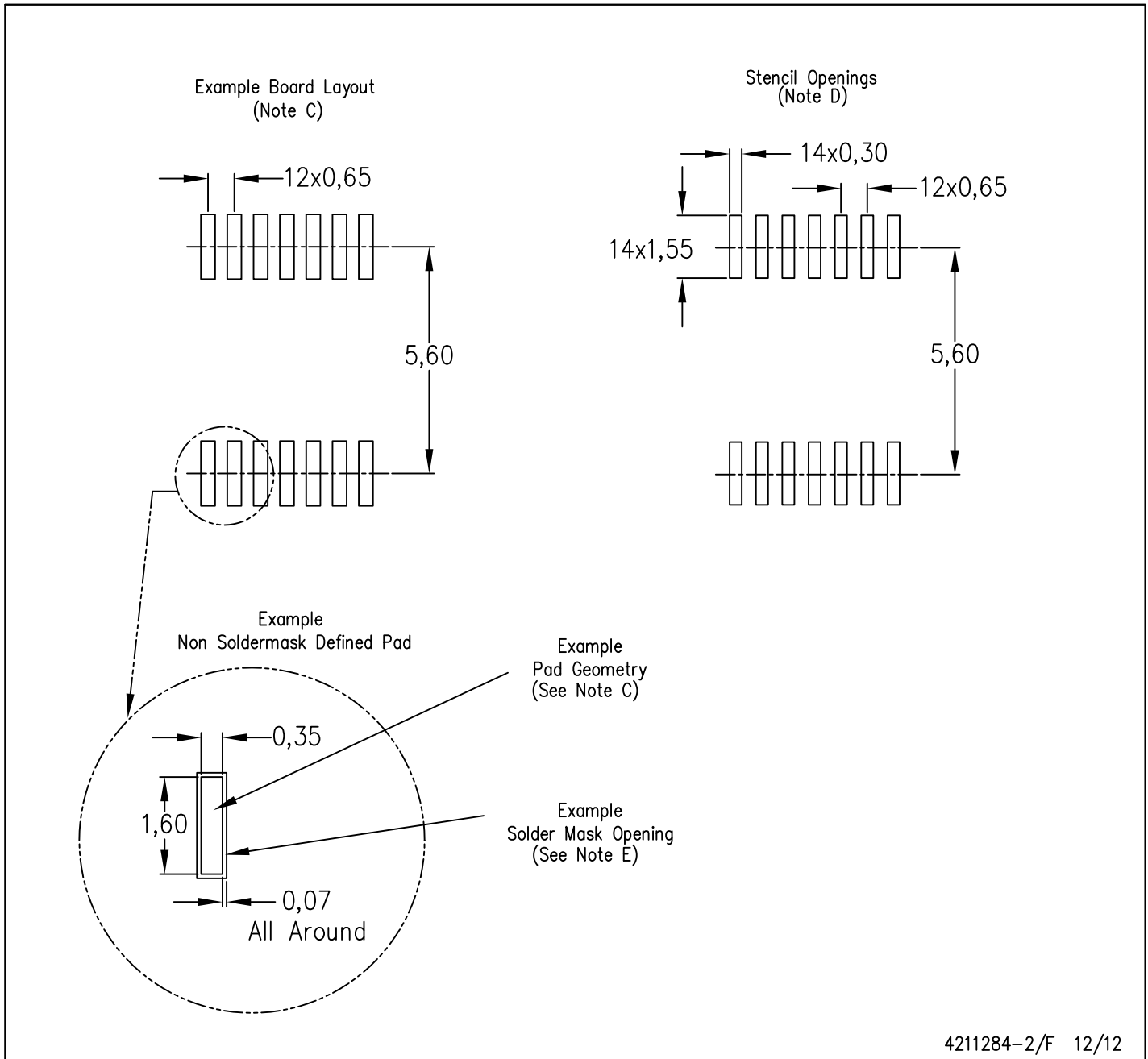
PLASTIC SMALL OUTLINE



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 -  Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0,15 each side.
 -  Body width does not include interlead flash. Interlead flash shall not exceed 0,25 each side.
 - E. Falls within JEDEC MO-153

PW (R-PDSO-G14)

PLASTIC SMALL OUTLINE



- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Publication IPC-7351 is recommended for alternate designs.
 - Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525 for other stencil recommendations.
 - Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

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